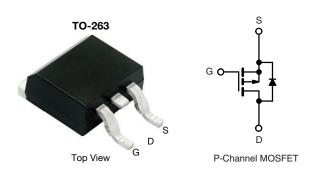
SQM50063EL

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Automotive P-Channel 60 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY				
V _{DS} (V)	-60			
$R_{DS(on)} (\Omega)$ at $V_{GS} = -10 V$	0.0058			
$R_{DS(on)}$ (Ω) at V_{GS} = -4.5 V	0.0110			
I _D (A)	-120			
Configuration	Single			

FEATURES

- TrenchFET[®] power MOSFET
- · Package with low thermal resistance
- 100 % R_g and UIS tested
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



ORDERING INFORMATION			
Package	TO-263		
Lead (Pb)-free and Halogen-free	SQM50063EL_GE3		

ABSOLUTE MAXIMUM RATINGS ($T_c = 25 \degree C$, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V _{DS}	-60	N	
Gate-Source Voltage		V _{GS}	± 20	V	
Continuous Drain Current	$T_C = 25 \ ^\circ C \ ^a$		-120		
	T _C = 125 °C		-85		
Continuous Source Current (Diode Conduction) ^a		I _S	-120	A	
Pulsed Drain Current ^b		I _{DM}	-480		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	-60		
Single Pulse Avalanche Energy		E _{AS}	180	mJ	
Maximum Power Dissipation	T _C = 25 °C	P _D	230	w	
	T _C = 125 °C		76		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +175	°C	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount ^c	R _{thJA}	40	°C/W
Junction-to-Case (Drain)		R _{thJC}	0.65	C/W

Notes

a. Package limited

b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %

c. When mounted on 1" square PCB (FR4 material)

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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static					•	•	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = -250 \mu A$		-60	-	-	v
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_D = -250 \mu\text{A}$		-2.0	-2.5	
Gate-Source Leakage	I _{GSS}	V _{DS} =	$V_{DS} = 0 V, V_{GS} = \pm 20 V$		-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$			-	-10	
		$V_{GS} = 0 V$	V _{DS} = -60 V, T _J = 125 °C	-	-	-50	μA
		$V_{GS} = 0 V$	V _{DS} = -60 V, T _J = 175 °C	-	-	-250	
On-State Drain Current ^a	I _{D(on)}	V _{GS} = -10 V	V _{DS} ≤ -5 V	-120	-	-	А
Drain-Source On-State Resistance ^a	D(01)	V _{GS} = -10 V	I _D = -30 A	_	0.0045	0.0058	
	R _{DS(on)}		I _D = -30 A, T _J = 125 °C	_	_	0.0089	Ω
		V _{GS} = -10 V		_	_	0.0107	
		$V_{GS} = -4.5 V$	$I_{\rm D} = -20 \rm{A}$	-	0.0078	0.0110	
Forward Transconductance ^b	g _{fs}		-15 V, I _D = -30 A	-	85	_	S
Dynamic ^b	313	100					
Input Capacitance	C _{iss}		V _{DS} = -25 V, f = 1 MHz	-	6943	9725	pF
Output Capacitance	Coss	V _{GS} = 0 V		_	3393	4750	
Reverse Transfer Capacitance	C _{rss}			_	139	195	
Total Gate Charge ^c	Qg			_	98	150	
Gate-Source Charge ^c	Q _{as}	V _{GS} = -10 V	V _{DS} = -30 V, I _D = -110 A	-	33	_	nC
Gate-Drain Charge ^c	Q _{gd}			-	11	-	
Gate Resistance	Rg		f = 1 MHz	1.2	2.55	3.9	Ω
Turn-On Delay Time ^c	t _{d(on)}				15	23	32
Rise Time ^c	t _r	-			10	15	ns
Turn-Off Delay Time ^c	t _{d(off)}	$\label{eq:VDD} \begin{array}{l} V_{\text{DD}} = \text{-30 V}, \ R_{L} = 0.27 \ \Omega \\ I_{\text{D}} \cong \text{-110 A}, \ V_{\text{GEN}} = \text{-10 V}, \ R_{g} = 1 \ \Omega \end{array}$			51	80	
Fall Time ^c	t _f				14	22	
Source-Drain Diode Ratings and Charac	•						
Pulsed Current ^a	I _{SM}			_	-	-480	А
Forward Voltage	V _{SD}	I _F = -100 A, V _{GS} = 0 V		-	-0.95	-1.5	V
Body diode reverse recovery time	t _{rr}	- - - - - - - - - - - - - - - - - - -		-	52	104	ns
Body diode reverse recovery charge	Qrr			-	44	88	nC
Reverse recovery fall time	ta			-	26	-	ns
Reverse recovery rise time	t _b			-	26	-	115
Body diode peak reverse recovery current	I _{RM(REC)}			-	-1.6	-	Α

Notes

a. Pulse test; pulse width $\leq 300~\mu\text{s},$ duty cycle $\leq 2~\%$

b. Guaranteed by design, not subject to production testing

c. Independent of operating temperature

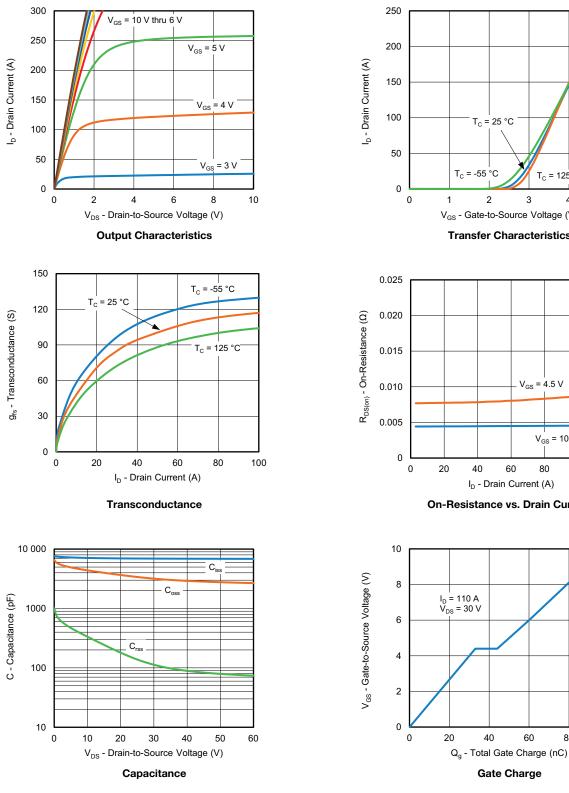
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

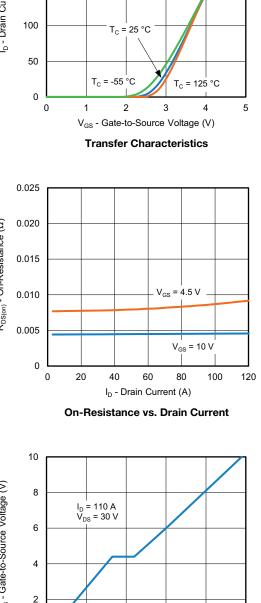
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TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)





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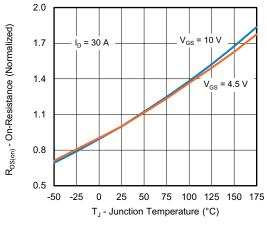
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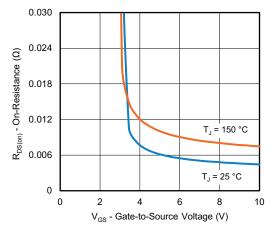


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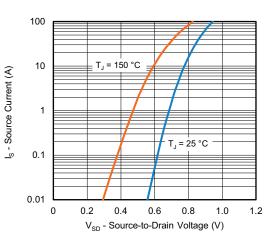
TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)



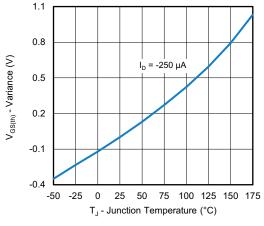
On-Resistance vs. Junction Temperature



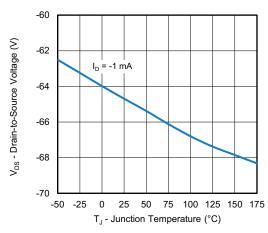
On-Resistance vs. Gate-to-Source Voltage



Source Drain Diode Forward Voltage



Threshold Voltage



Drain Source Breakdown vs. Junction Temperature

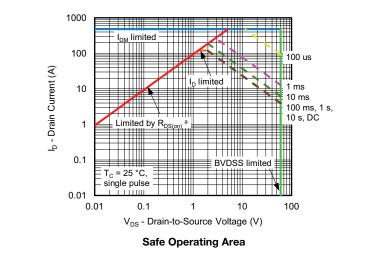
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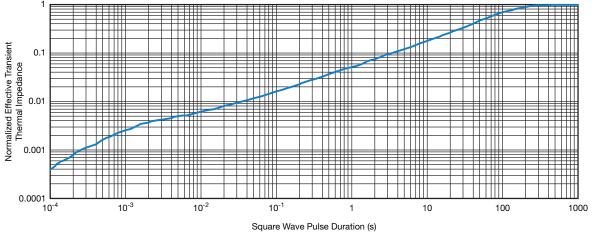


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THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)





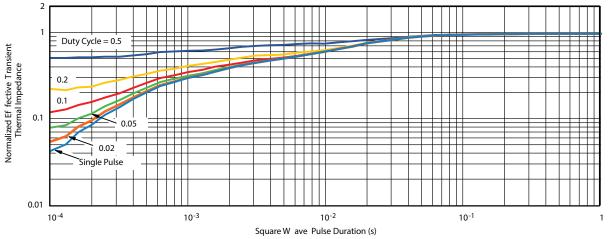
Normalized Thermal Transient Impedance, Junction-to-Ambient



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THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Note

The characteristics shown in the two graphs

- Normalized Transient Thermal Impedance Junction to Ambient (25 °C)

- Normalized Transient Thermal Impedance Junction to Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

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